



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

TESSERA 3.3-018

In 1996 patent application of  
Khandros et al.

Serial No.: 08/030,194

Filed: April 28, 1993

For: SEMICONDUCTOR CHIP ASSEMBLIES,  
METHODS OF MAKING SAME AND  
COMPONENTS FOR SAME

:  
: Group Art Unit: 2503  
:  
: Examiner: S. Clark  
:  
: Date: April 18, 1996  
:

Assistant Commissioner For Patents  
Washington, D.C. 20231

RECEIVED

MAY 06 1996

GROUP 2500

# RESPONSE

Sir:

In response to the Official Action mailed October 27, 1995,  
please amend the above-identified application as follows:

## In the Claims:

In claim 1, line 1 change "chip comprising" to read --  
chip assembly comprising --.

Amend claim 63 as follows:

10. 63. (Twice Amended) A module as claimed in claim  
62 wherein each said sheetlike element includes a thin, flexible,  
top layer and wherein said [complaint] compliant layer of each  
said sheetlike element is disposed between said top layer and  
said front surface of each said chip.

In claim 67, line 8 change "compressible" to read --  
compliant --.

In claim 68, line 10 change "compressible" to read --  
compliant --.

In claim 69, line 6 change "compressible" to read --  
compliant --.

I hereby certify that this correspondence is being deposited with the  
United States Postal Service with sufficient postage as First Class mail  
in an envelope addressed to Assistant Commissioner for Patents,  
Washington, D.C. 20231 on April 18, 1996.

(Signature)

MARCUS J. MILLET

Typed or Printed Name of Person Signing Certificate